

SAF-T-LOK[®]

Debond

Technical Data Sheet

For Cured Cyanoacrylate Adhesives

GENERAL INFORMATION: SAF-T-LOK's **Debond** is extremely effective for dissolving cyanoacrylate bonds, or removing excess cured adhesive. It is useful for changing part locations and cleaning unwanted cured adhesive from parts. It is not recommended for use on acrylic plastics.

PHYSICAL PROPERTIES

Solvent Base	Nitromethane/Acetone
Boiling Point	133+°F
Color	Clear, Straw Colored Liquid
Specific Gravity	1.06
Flash Point	Approx, 1°F (TCC)
Vapor Density	2.1 (Air = 1)

DIRECTIONS FOR USE

Immerse bonded parts in **Debond** until the bond loosens or weakens sufficiently for easy disassembly or removal. Or, repeatedly apply **Debond** to the adhesive until parts can be disassembled or the adhesive scraped away.

TYPICAL APPLICATIONS

- Cleaning dispensing needles
- Debonding parts for engineering changes
- Cleaning jigs and fixtures used in production

HANDLING AND STORAGE

Use only in well ventilated areas free from sparks and open flames. Avoid over exposure to vapor, and avoid direct contact with eyes and skin. Wear protective clothing. Wash hands with soap and water after use. Remove contaminated clothing and launder before reuse.

Debond is volatile and flammable. Keep away from any source of ignition such as heat, sparks, and open flames. Ground all containers when transferring liquid; store in tightly closed containers in a cool, well ventilated area. Do not eat or smoke where **Debond** is being used.

IMPORTANT NOTICE: All statements and technical data contained herein are based on tests we believe to be reliable, but the accuracy of completeness thereof is not guaranteed. It is recommended that the buyer test this product to determine its suitability for his application before use. **SAF-T-LOK Corporation** is not responsible for loss, claim or damages resulting from use of its products